



Product Change Notification: DSN0-05KPVH284

Date:

08-Apr-2026

Product Category:

8-Bit Microcontrollers, Memory

Notification Subject:

CCB 8189 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material and QMI519 as a new die attach material for selected 25AA128, 25AA256, 25LC128, 25LC256, AT25256B, AT25M01, ATtiny13, ATtiny13A, ATtiny25, ATtiny45 and ATtiny85 device families available in 8L SOIJ (.208in) package at MTAI assembly site.

Affected CPNs:

[DSNO-05KPVH284_Affected_CPN_04082026.pdf](#)

[DSNO-05KPVH284_Affected_CPN_04082026.csv](#)

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected:

Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material and QMI519 as a new die attach material for selected 25AA128, 25AA256, 25LC128, 25LC256, AT25256B, AT25M01, ATtiny13, ATtiny13A, ATtiny25, ATtiny45 and ATtiny85 device families available in 8L SOIJ (.208in) package at MTAI assembly site.

Pre and Post Summary Changes:

	Pre Change	Post Change	Change (Yes/No)

Assembly Site	Microchip Technology Thailand (HQ) (MTAI)	Microchip Technology Thailand (HQ) (MTAI)	No
Wire Material	Au	CuPdAu	Yes
Die Attach Material	8390A (PFAS-free)	QMI519 (PFAS-free)	Yes
Molding Compound Material	G600V	G600V	No
Lead-Frame Material	CDA194	CDA194	No

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability by qualifying palladium coated copper with gold flash (CuPdAu) as a new wire material and QMI519 as a new die attach material.

Change Implementation Status: In Progress

Estimated First Ship Date: 10 July 2026 (date code: 2628)

Note Below EFSD: Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	April 2026						>	July 2026				
Work Week	14	15	16	17	18			27	28	29	30	31
Qual Report Availability		x										
Final PCN Issue Date		x										
Estimated Implementation Date									x			

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: April 08, 2026: Issued final notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

[PCN_DSNO-05KPVH284_Qualification Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our [PCN home page](#) select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the [PCN FAQ](#) section.

If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected Catalog Part Numbers (CPN):

ATTINY13A-SFR
ATTINY13A-SN
ATTINY13A-SF
ATTINY13A-SURA4
ATTINY13A-SNR
ATTINY13A-SU
ATTINY13A-SUR
ATTINY13-20SU
ATTINY13-20SUR365
ATTINY13-20SUR
ATTINY13V-10SUR
ATTINY13V-10SU
ATTINY85V-10SUR
ATTINY85-20SUR
ATTINY85-20SU
ATTINY85V-10SU
ATTINY85-20SF
ATTINY85-20SFR
ATTINY45-20SU
ATTINY45-20SUR
ATTINY45V-10SUR
ATTINY45V-10SU
ATTINY25-20SUR
ATTINY25-20SNR
ATTINY25-20SN
ATTINY25V-10SUR
ATTINY25V-10SNR
ATTINY25V-10SU
ATTINY25-20SU
ATTINY25V-10SN
25AA128-I/SM
25LC128T-E/SM

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25LC128T-I/SM

25LC128-I/SM

25LC128-E/SM

25AA128T-I/SM

25AA256-I/SM

25AA256T-I/SM

25LC256T-E/SM

25LC256T-I/SM

25LC256-I/SM

25LC256-E/SM

AT25256B-SHL-T

AT25256B-SHL-B

AT25M01-SHM-T

AT25M01-SHM-B